# Product Data Sheet

## hm2.0 Terminal Block, Type A, Part No. 243-11010-15

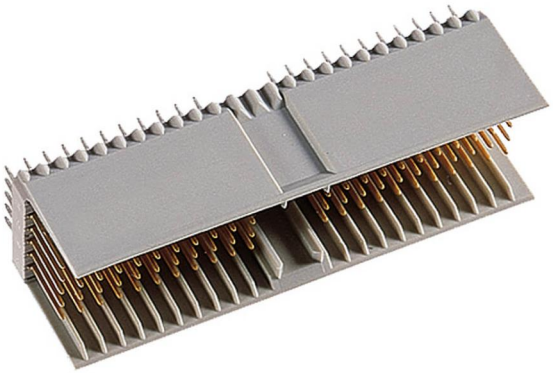
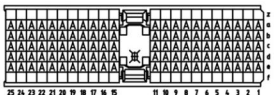


Illustration similar





Perpendicular



Press-fit

- Number of poles: 110
- Connector length: 3.7 mm
- for PCB thickness > 2.2 mm
- Tested in accordance with IEC 61076-4-101

» to product on www.ept.de

» to product group hm 2.0



**ept GmbH** | Bergwerkstr. 50 | 86971 Peiting | Tel. +49 (0) 8861 / 25 01 0 | Fax +49 (0) 8861 / 55 07 | sales@ept.de | **www.ept.de**

Downloaded from Arrow.com.

# Product Data Sheet

## hm2.0 Terminal Block, Type A, Part No. 243-11010-15

## Technical Specifications

### Basics

| | |
|---|---|
| Specification | IEC 61076-4-101 |
| Performance Level | 2 |
| No. of Contacts | 110 |
| Termination Technology | Press-fit technology |
| Termination Length | 3.7 mm |
| Operating Temperature Range | -55°C to +125°C |

### Material

| | |
|---|---|
| Insulator Material | Glass-fiber-reinforced PBT, UL 94 V-0 |
| CTI value<br>*IEC 60112* | 200 |
| Contact Material | Bronze |

### Mechanical

| | |
|---|---|
| Pitch | 2.0 mm |
| Mating Force per Pin | Contact: max. 0.75 N, Shielding: max. 1 N |
| Separating Force per Pin | Contact: min. 0.15 N, Shielding: min. 0.15 N |
| Durability | > 250 insertion cycles |

### Electrical

| | |
|---|---|
| Operational Current | 1.5 A at +20°C, 1.0 A at +70°C |
| Test Voltage | 750 V r.m.s. |
| Contact Resistance | max. 20 mΩ |
| Clearance and Creepage | ≥ 0.8 mm |
| Insulation Resistance | at least $10^4$ MΩ |
| Data Transfer Rate | 3.125 Gbit/s |

### Approval / Compliance

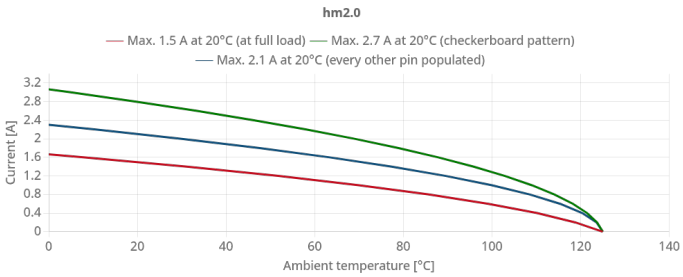
| | |
|---|---|
| UL file | E130314 |
| Environment | RoHS compliant |



**ept GmbH** | Bergwerkstr. 50 | 86971 Peiting | Tel. +49 (0) 8861 / 25 01 0 | Fax +49 (0) 8861 / 55 07 | sales@ept.de | **www.ept.de**

Downloaded from Arrow.com.

## Derating Diagram



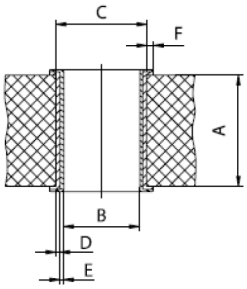




Downloaded from Arrow.com.

### Hole Specifications

Plated through-hole according to IEC 60352-5




| Material | chem. Sn Schicht |
|---|---|
| **Nennloch** | **Ø 0.6 mm** |
| **A Leiterplattendicke** | min. 2.2 mm |
| **B Endloch** | Ø 0.60 ±0.05 mm |
| **C Grundbohrung** | 0.70 ±0.02 mm |
| **D Cu Schicht** | min. 25 µm |
| **E Oberfläche** | max. 1.5 µm; chem. Sn Leiterplatten |
| **F Restring** | min. 0.1 mm |

| Material | Ni, Au Leiterplatten |
|---|---|
| **Nennloch** | **Ø 0.6 mm** |
| **A Leiterplattendicke** | min. 2.2 mm |
| **B Endloch** | Ø 0.60 ±0.05 mm |
| **C Grundbohrung** | 0.70 ±0.02 mm |
| **D Cu Schicht** | min. 25 µm |
| **E Oberfläche** | Ni, Au Schicht, 0.05 - 0.2 µm Au über 2.5 - 5 µm Ni |
| **F Restring** | min. 0.1 mm |

| Material | rein Cu Leiterplatten |
|---|---|
| **Nennloch** | **Ø 0.6 mm** |
| **A Leiterplattendicke** | min. 2.2 mm |
| **B Endloch** | Ø 0.60 ±0.05 mm |
| **C Grundbohrung** | 0.70 ±0.02 mm |
| **D Cu Schicht** | min. 25 µm |
| **E Oberfläche** | OSP*,z.B. GLICOAT-SMD (F2) mit 0.12 - 0.15 µm |
| **F Restring** | min. 0.1 mm |

| Material | HAL Sn Leiterplatten |
|---|---|
| **Nennloch** | **Ø 0.6 mm** |
| **A Leiterplattendicke** | min. 2.2 mm |
| **B Endloch** | Ø 0.60 ±0.05 mm |
| **C Grundbohrung** | 0.70 ±0.02 mm |
| **D Cu Schicht** | min. 25 µm |
| **E Oberfläche** | HAL Sn, 5 - 15 µm |
| **F Restring** | min. 0.1 mm |




Downloaded from Arrow.com.

## Modifications

Available on request

- Special configuration
- Other contact coatings

## Accessories

» hm2.0 Kodiereinsatz Messerleiste Artikelnummer 243-8031

» hm2.0 Kodiereinsatz Messerleiste Artikelnummer 243-8014

» hm2.0 Kodiereinsatz Messerleiste Artikelnummer 243-8012

## Drawings

Component data in 2D and 3D format you can download here:

» PDF » 3D IGES » 3D STEP » 3D PDF




Downloaded from Arrow.com.